

江西省晶能半导体有限公司
Jiangxi LatticePower Semiconductor Corporation

产 品 规 格 书
Specification

产品名称 Product Name:	LQJ1-C
产品型号 Product P/N:	MQ
客 户 Client Name:	
客户料号 Client P/N:	
版 本 号 Version No.:	A00
日 期 Sending Date:	2025.04

工厂地址:江西省南昌市高新区艾溪湖北路 699 号

Address: No.699 Aixihu North Road, Nanchang, Jiangxi Province, China

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1、特点 Features

- ◆ EMC 封装，高亮度，高可靠性，主要用于汽车应用
EMC package, high brightness, high reliability, it is mainly used in automotive applications
- ◆ 尺寸：2.70mm*2.00mm*0.60mm
Size: 2.70mm*2.00mm*0.60mm
- ◆ 颜色：根据 CIE 1931 色度标准分档
Color: according to CIE 1931 chromaticity
- ◆ 通过 RoHS 认证
RoHS compliant
- ◆ MSL 等级 2a
MSL 2a
- ◆ 通过 AEC-Q102
AEC-Q102 qualified
- ◆ 适于 SMT 贴片
Compatible with SMT
- ◆ 发光角度：120°
Viewing angle: 120°
- ◆ 包装：最大 3000 颗/卷
Package: max 3000pcs /reel



2、应用 Applications

汽车内外部照明

Interior and exterior lighting for automotive



3、性能 Performance

a) 极限参数 Maximum Ratings

项目 Item	符号 Symbol	参数 Rating	单位 Unit
最大正向电流 Max DC Forward Current	I_F	250	mA
电功率 Electrical Power	P	0.7	W
峰值正向电流 Peak Forward Current	I_{FP}	500	mA
结温 (DC 模式) LED Junction Temperature (DC mode)	T_j	150	°C
工作温度 Operating Temperature Range	T_{opr}	-40~125	°C
存储温度 Storage Temperature Range	T_{stg}	-40~125	°C
ESD (人体模式) ESD (Human Body Mode)	HBM	8000	V

备注 Notes :

◇ 环境温度 $T_a=25^{\circ}\text{C}$

Ratings at $T_a=25^{\circ}\text{C}$.

◇ I_{FP} 脉冲时间 $\leq 100\mu\text{s}$, 占空比 $\leq 3\%$

I_{FP} Conditions with pulse $\leq 100\mu\text{s}$ and duty cycle $\leq 3\%$.

b) 光电参数 Electro-Optical Characteristics (T solder pad =25 °C, I_F =200mA)

项目 Item	符号 Symbol	最小值 Min.	典型值 Typ.	最大值 Max.	单位 Unit
光通量 Luminous Flux	Φ_V	31	42	56.8	lm
正向电压 Forward Voltage	V_F	2.75	3.05	3.50	V
色坐标 Color Coordinate	C _x	--	0.068	--	
	C _y	--	0.4	--	
主波长 Dominant wavelength	WLD	490	495	500	nm
齐纳管电压 Zener Voltage (I _Z =5mA)	V_Z	12	--	16	V
反向电压 Reverse Voltage (I _R =10mA)	V_R	0.7		1.2	V
实际热阻 PN/焊点 Real Thermal Resistance (Junction to Solder Point)	R _{thJS real}		37	48	°C/W
电热阻 PN/焊点 Electrical Thermal Resistance (Junction to Solder Point)	R _{thJS elec}		27	35	°C/W
发光角度 Viewing Angle	2 θ		120		°
光电转换效率 Efficiency	η		27		%

4、产品代码 Product Order Code

MQ - N - B - C3A - DD7
 ① ② ③ ④ ⑤

- ① 产品型号 Product Type (MQ: LQJ1-C)
- ② 显色指数 Ra Level
- ③ 色温区块 Color Bin
- ④ 亮度等级 Brightness Level
- ⑤ 电压等级 VF Level

出货标签(例) Shipping label (e.g.)



LatticePower Corporation Limited

Item: MQ-N-B-C3A-DD7 LQJ1-C



Reel ID: AMQC00000001

MSL 2a



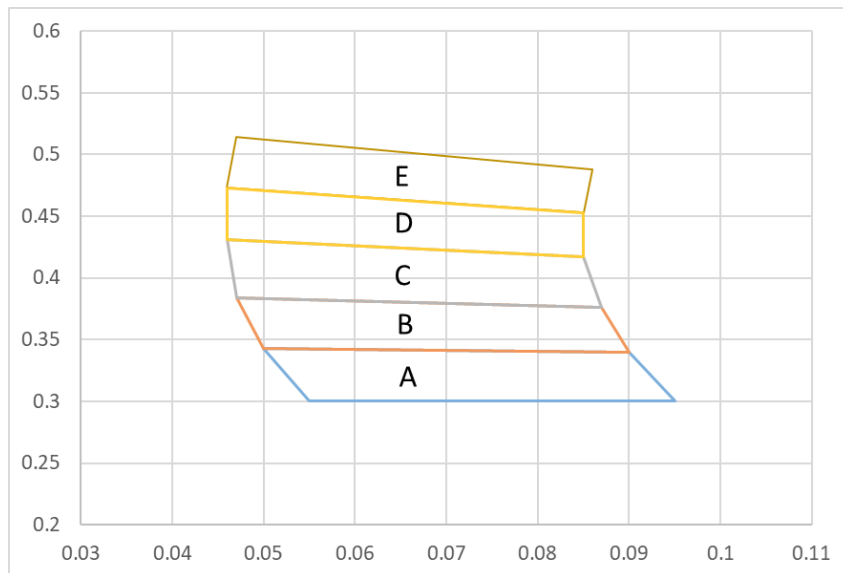
Qty: 3000 6MQDCACA



Date: 2024-10-12

5、分档规则 Bin Regulations

a) 色度区域 Chromaticity Regions (T solder pad = 25°C, I_F = 200mA)



Color Chromaticity Groups					
Color Bin	Cx	Cy	Color Bin	Cx	Cy
A	0.0500	0.3430	B	0.0470	0.3840
	0.0900	0.3400		0.0870	0.3760
	0.0950	0.3000		0.0900	0.3400
	0.0550	0.3000		0.0500	0.3430
C	0.0460	0.4310	D	0.0460	0.4730
	0.0850	0.4170		0.0850	0.4530
	0.0870	0.3760		0.0850	0.4170
	0.0470	0.3840		0.0460	0.4310
E	0.0470	0.5140			
	0.0860	0.4880			
	0.0850	0.4530			
	0.0460	0.4730			

b) 亮度分档 Luminous Flux Groups (T solder pad = 25°C, I_F =200mA)

Group Code	Min.(lm)	Max.(lm)
C2A	31	36
C3A	36	41.5
M10	41.5	45.7
M11	45.7	51.7
N2	51.7	56.8

c) 电压分档 Voltage Groups (T solder pad = 25°C, I_F =200mA)

Group Code	Min.(V)	Max.(V)
DD6	2.75	3.00
DD7	3.00	3.25
DD8	3.25	3.50

d) 显指分档 Ra Groups (T solder pad = 25°C, I_F =200mA)

Group Code	Min.	Max.
N	0	100

备注 Notes :

- ✧ 亮度测试存在±8%公差
It maintains a tolerance of ±8% on luminous flux measurements.
- ✧ 电压测试存在±0.1V 公差
It maintains a tolerance of ± 0.1V on Forward voltage measurements.
- ✧ 色度坐标(Cx, Cy)存在±0.006 公差
The chromaticity coordinates(Cx, Cy) guarantee should be added ±0.006 tolerance.

6、光电特性图 The Photoelectric Characteristics Graph

Fig 1. 辐射特性 Radiation Characteristics

$I_F = 200\text{mA}$; $T_S = 25^\circ\text{C}$

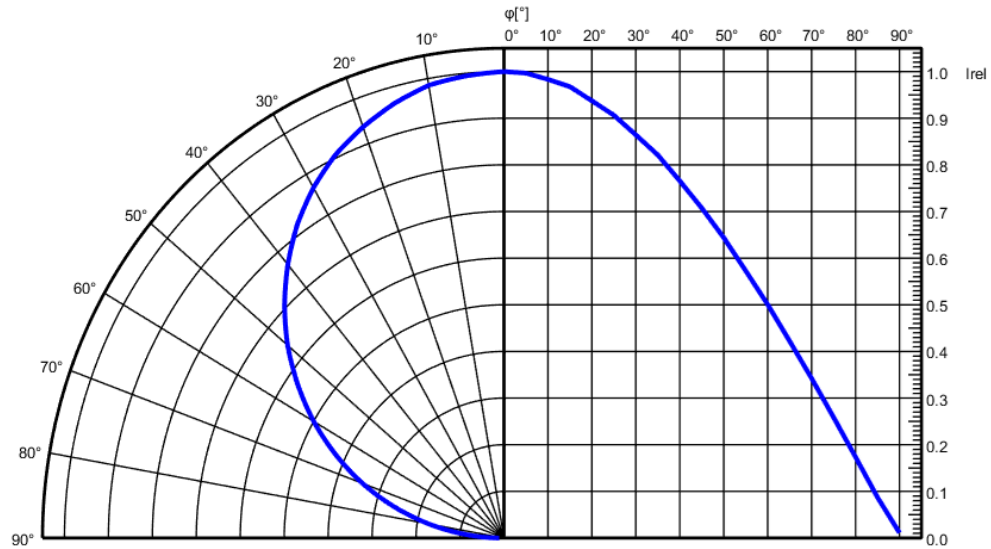


Fig 2. 相对发光光谱 Relative Spectral Distribution vs. Wavelength

$\Phi_{rel} = f(\lambda)$; $I_F = 200\text{mA}$; $T_S = 25^\circ\text{C}$

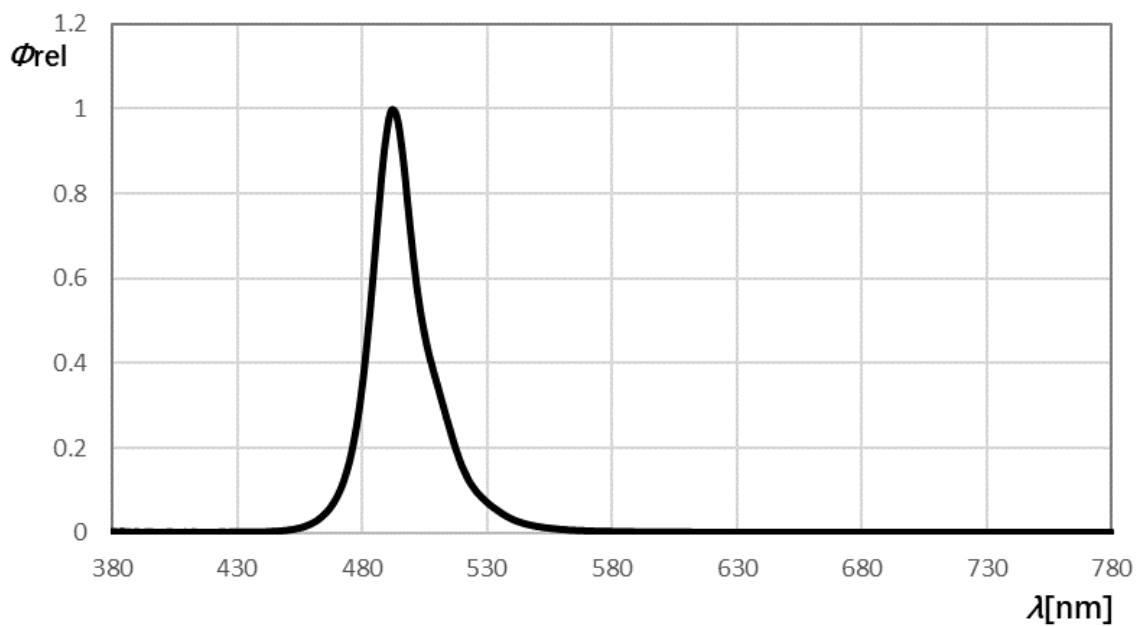


Fig 3. 正向电压 Forward Voltage

$$I_F = f(V_F); T_S = 25^\circ\text{C}$$

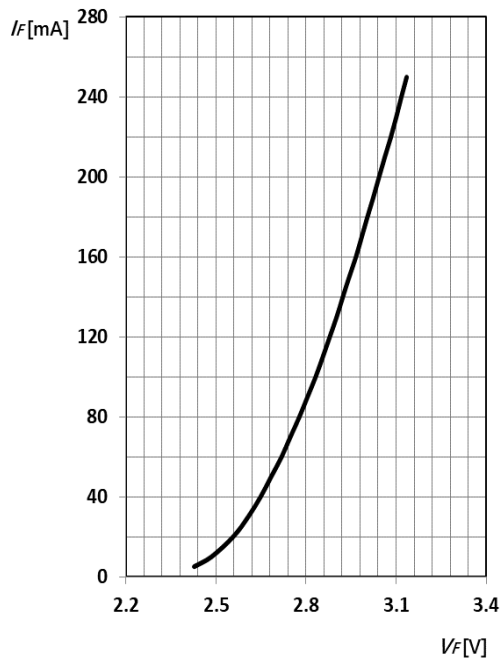


Fig 4. 相对发光强度 Relative Luminous Flux

$$\Phi_V / \Phi_V(200\text{mA}) = f(I_F); T_S = 25^\circ\text{C}$$

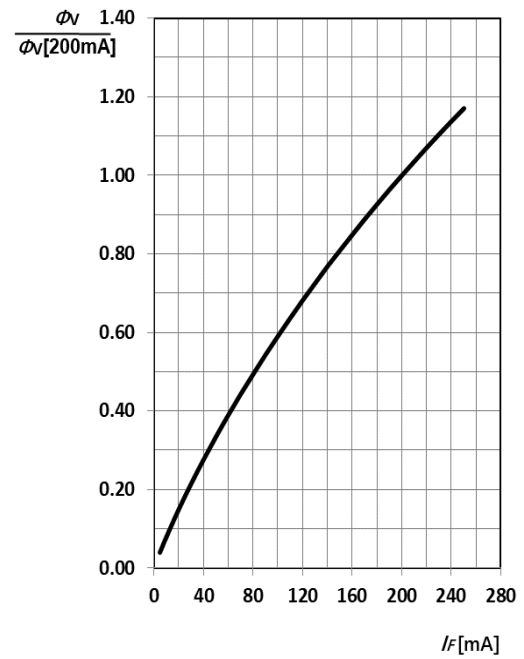


Fig 5. 波长偏移 Dominant Wavelength Shift

$$\Delta\lambda_D = \lambda_D - \lambda_D(200\text{mA}) = f(I_F); T_S = 25^\circ\text{C}$$

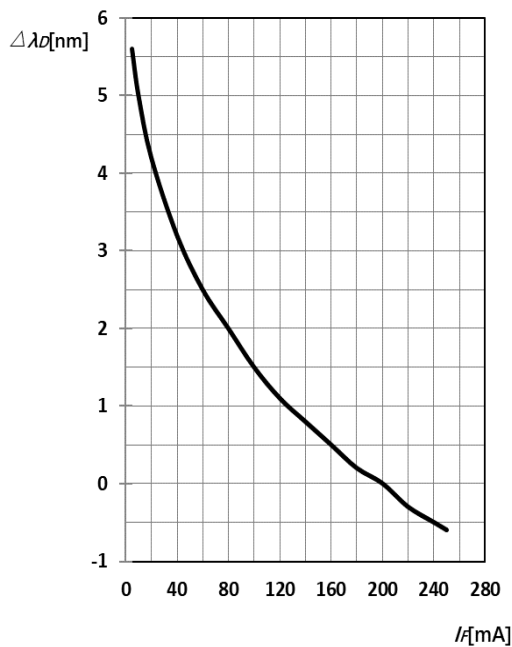


Fig 6. 正向电压 Forward Voltage

$$\Delta V_F = V_F - V_F(25^\circ\text{C}) = f(T_j); I_F = 200\text{mA}$$

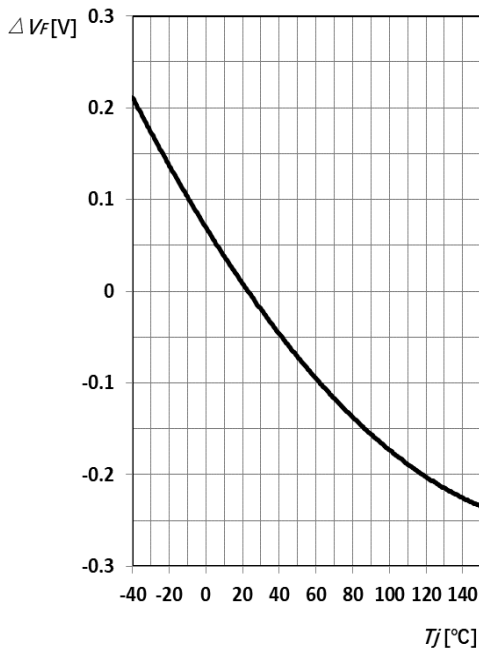


Fig 7. 相对发光强度 Relative Luminous Flux

$$\Phi_V / \Phi_V(25^\circ\text{C}) = f(T_j); I_F = 200\text{mA}$$

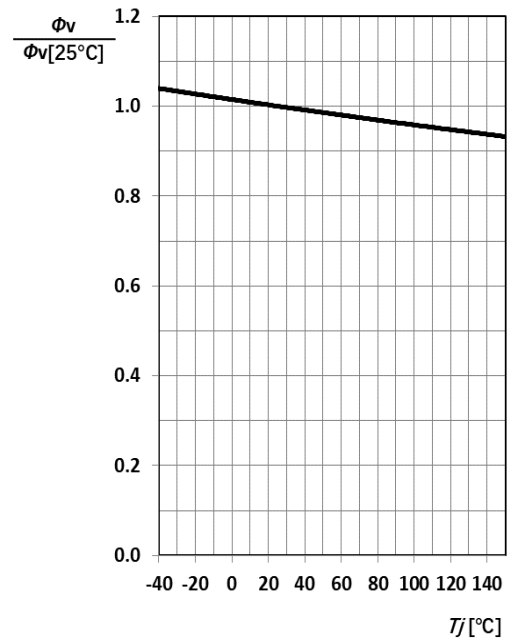


Fig 8. 波长偏移

Dominant Wavelength Shift

$$\Delta \lambda_D = \lambda_D - \lambda_D(25^\circ\text{C}) = f(T_j); I_F = 200\text{mA}$$

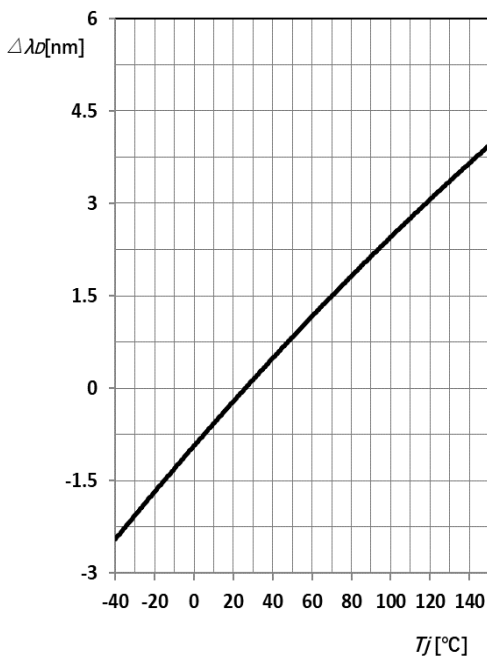
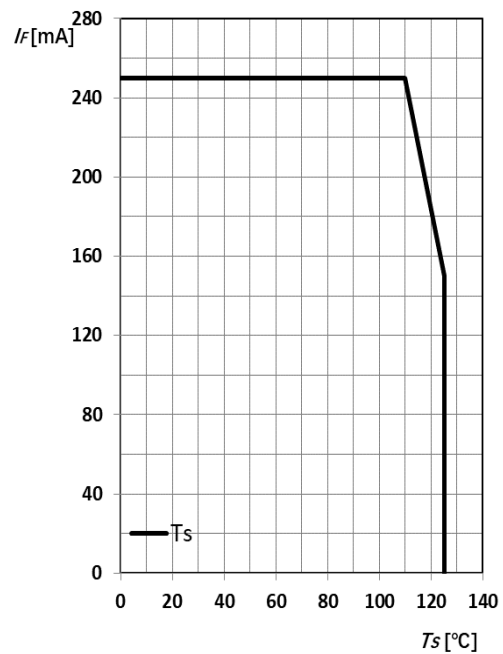


Fig 9. 最大正向电流

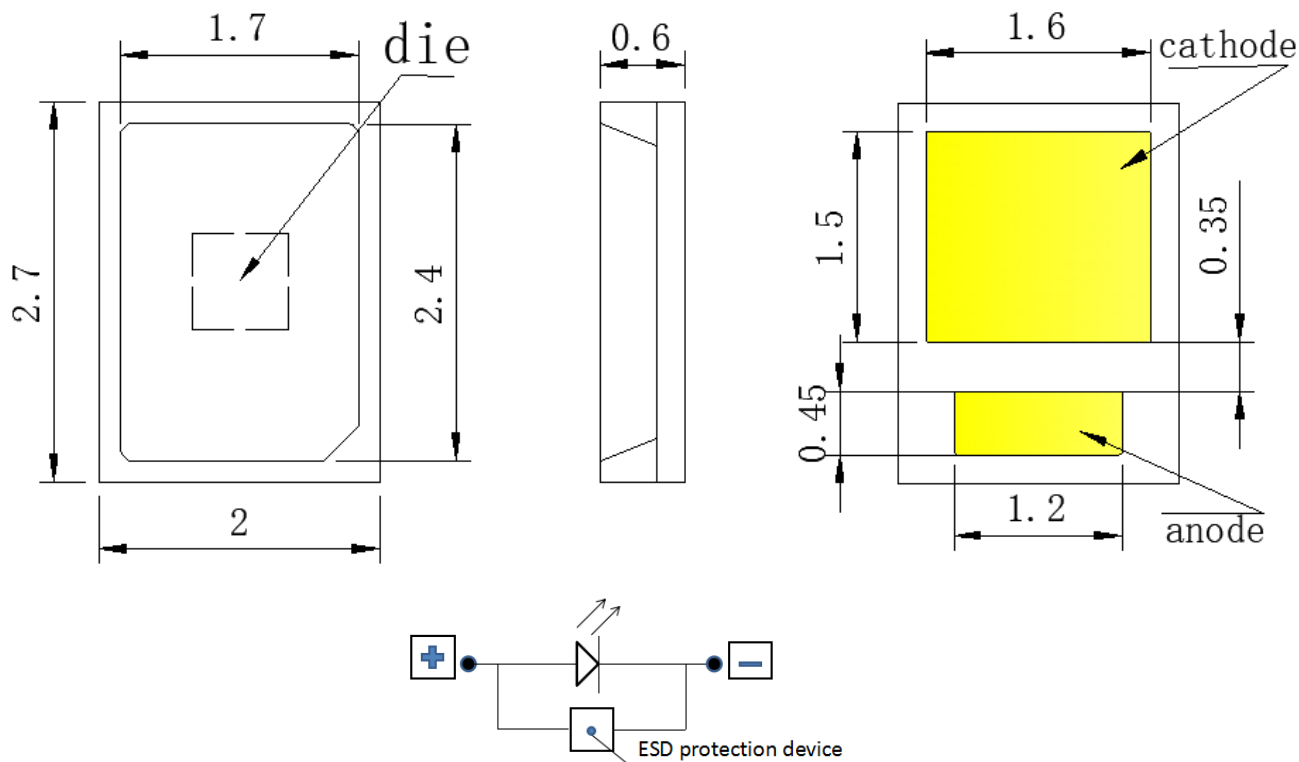
Max. Permissible Forward Current

$$I_F = f(T_s)$$

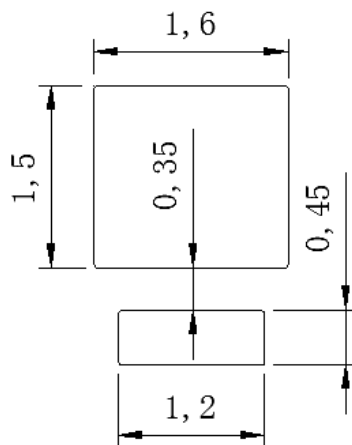


7、产品及焊盘尺寸 Product and Soldering Pattern Dimensions

a) 产品尺寸 Product Dimensions



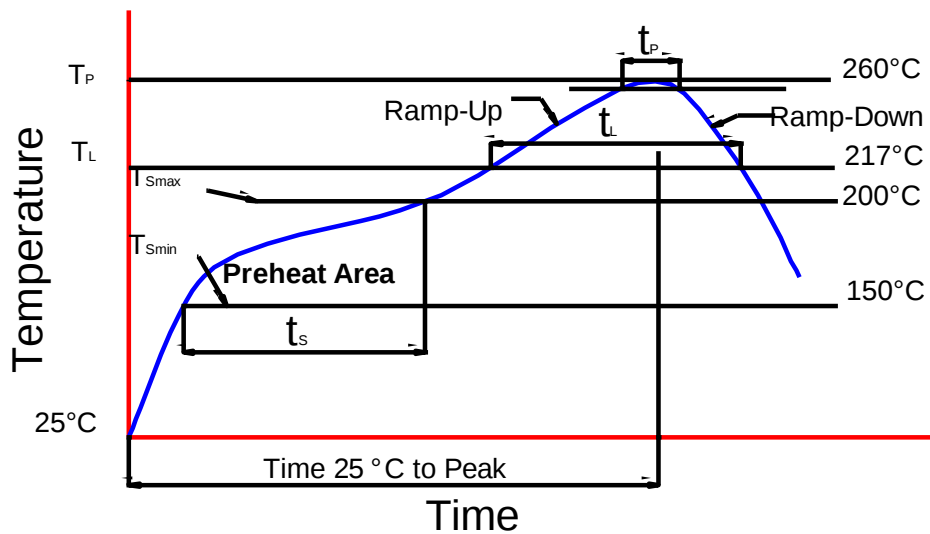
b) 焊盘尺寸 Soldering Pattern Dimensions



注 Notes:

- ◇ 所有尺寸均以 mm 为单位
All dimensions are in millimeters.
- ◇ 尺寸公差±0.1mm
Dimension tolerance ± 0.1mm.
- ◇ 灯珠近似重量: 10.6mg
Approximate weight: 10.6mg.

8、回流焊曲线 Reflow Soldering Profile

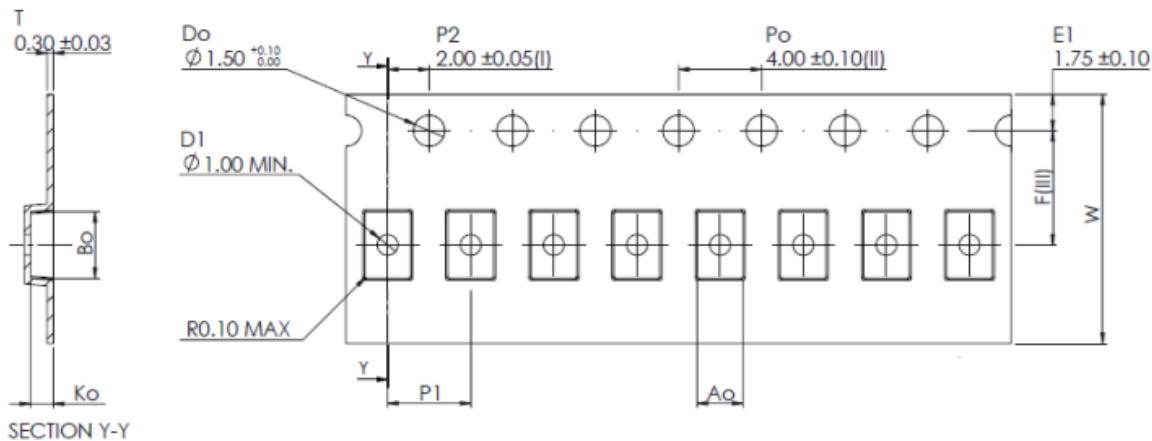


根据 JEDEC-J-STD-020E, 参考以下参数:

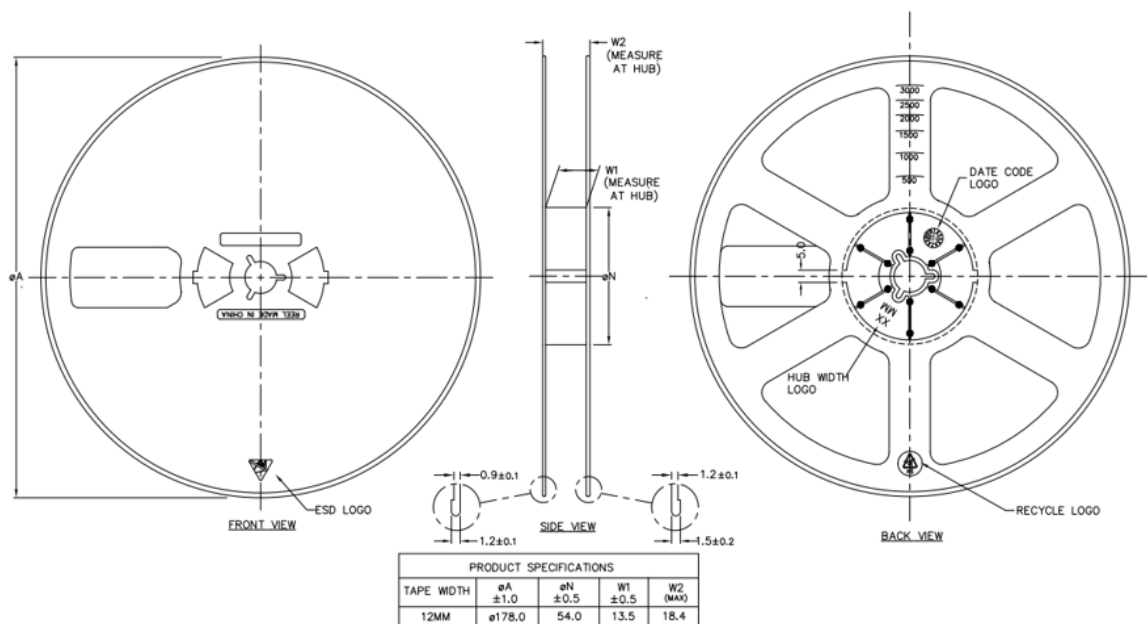
Compatible with the JEDEC-J-STD-020E, refer to the parameters as below

特制参数 Profile Feature	无铅焊料 Lead-Free Solder
平均上升速率 (T_{smax} 至 T_p) Average Ramp-Up Rate (T_{smax} to T_p)	3 °C/sec max
预热: 温度最小值 (T_{smin}) Preheat: Temperature Min (T_{smin})	150°C
预热: 最高温度 (T_{smax}) Preheat: Temperature Max (T_{smax})	200°C
预热: 时间 (t_{smin} 到 t_{smax}) Preheat: Time (t_{smin} to t_{smax})	60-180 secs
回流温度 (T_L) Time Maintained Above: Temperature (T_L)	217°C
回流时间 (t_L) Time Maintained Above: Time (t_L)	60-150 secs
峰值/分类温度 (T_p) Peak/Classification Temperature (T_p)	255±5°C
实际峰值温度 (T_p) 在 5°C 以内的时间 Time Within 5°C of Actual Peak Temperature (T_p)	20~40 secs
降低速率 Ramp-Down Rate	4°C/sec max.

9、載帶及卷軸 Tape and Reel



Ao	2.20 +/- 0.05
Bo	3.20 +/- 0.05
Ko	1.10 +/- 0.05
F	5.50 +/- 0.05
P1	4.00 +/- 0.10
W	12.00 +0.30/- 0.10



备注 Notes:

- ✧ 卷轴包装数量: 3000pcs

Units per Reel: 3000pcs.

- ✧ 卷轴包装方法符合 JIS C 0806 (连续胶带上的电子元件包装)

The tape packing method complies with JIS C0806 (Packing of Electronic Components on Continuous Tapes).

- ✧ 当卷轴由于工作中断而重绕时, 载带上压力不应超过 10N, 否则 LED 可能会粘在盖带上

When the tape is rewound due to work interruptions, no more than 10N should be applied to the embossed carrier tape.

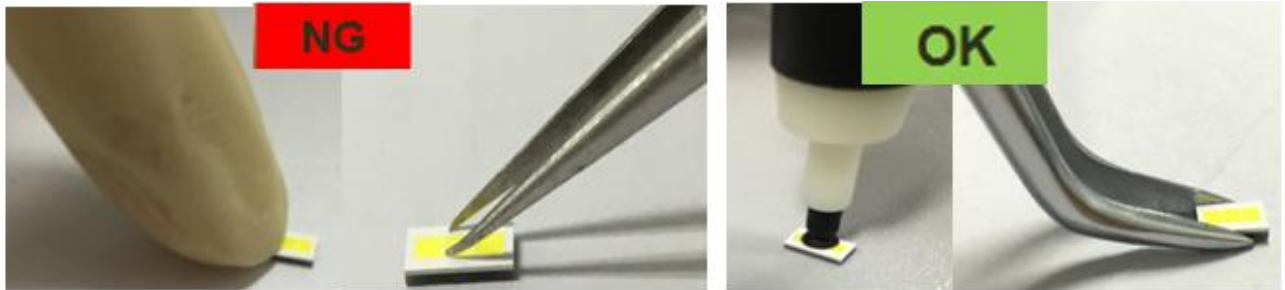
The LEDs may stick to the cover tape.

10、注意事项 Cautions

a) 存储 Storage

- 即使未开封，也不要将产品放在潮湿的地方。建议存放温度在 5°C~30°C 之间，相对湿度在 30% 以下。
Even if unopened, do not store the product in a high humidity place. The recommended storage temperature is between 5°C and 30°C, and the relative humidity should be below 30%.
- 打开包装后建议在 24 小时内过完回流焊，车间条件 $\leq 30^{\circ}\text{C}/60\%\text{RH}$ 。
It is recommended to finish the reflow soldering process within 24 hours after opening the package. The workshop conditions should be $\leq 30^{\circ}\text{C}/60\%\text{RH}$.
- 本产品为 MSL 2a，如果开封后未能在期限内完成组装，再次使用前需将贴片卷盘放入 60°C 烤箱烘烤 24 小时后才能确保安全使用。建议使用后的余料可重新密封在原始真空袋中。
This product is MSL 2a. If the assembly is not completed within the specified time after opening, to ensure the quality, the tape and reel should be baked in a 60°C oven for 24 hours before reuse. It is recommended to reseal any unused material in the original vacuum bag.
- 不要接触任何未知的液体，特别是丙酮。
Do not come into contact with any unknown liquids, especially acetone.
- 防止静电损伤，手动操作需要在静电防护环境下，同时作业员需佩戴静电环。
To prevent electrostatic damage, manual operations should be performed in an electrostatic-protected environment, and operators should wear anti-static rings.

b) 操作注意 Handling Precautions



- 在处理过程中，应注意确保组件顶面不会受到压力或碰撞。
During the handling process, it is crucial to ensure that the top surface of the component is not subjected to any pressure or impact.
- 应避免使用所有类型的尖锐物体（例如镊子，指甲等），以防止对硅树脂造成压力，因为这会导致部件损坏。
The use of all types of sharp objects, such as tweezers and fingernails, should be avoided to prevent applying pressure to the silicone resin, as this can lead to component damage.

11、文件履历表 Document Resume

序号	变更日期	变更人	版本	变更内容
01	2024.10.12	曾海强	Y00	1.新制定；
02	2025.03.20	曾海强	Y01	1.更新亮度上下限范围；
03	2025.04.22	曾海强	A00	1.添加产品图片 2.转正式版本；